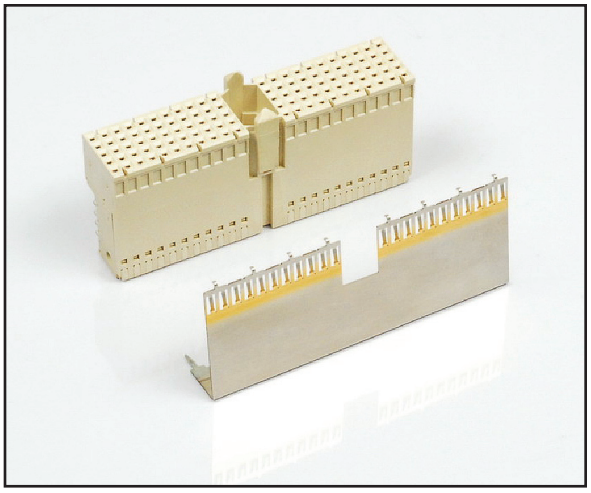
3M™ CP2 Press-Fit Socket

2 mm Type A 110 Signal Contacts Right Angle CP2 Series



- 25mm basic system unit
- 50mm module
- Designed according to IEC 61076-4-101 and IEC 60352-5 Standards
- 2 mm grid spacing allows for high signal density at low cost
- "Eye of the Needle" compliant pin press-fit design reduces manufacturing time and cost
- Additional grounding row available for improved ground bounce and EMI immunity
- Mates with 5 row 3M™ MetPak™ HM, and CP2 headers
- End-to-end stackable with 5 row 3M™ MetPak™ HSHM, HM, and CP2 sockets
- See Regulatory Information Appendix (RIA) for chemical compliance information

Date Modified: February 15, 2008

Physical

Insulation:	
Material:	High Temperature Thermoplastic (LCP)
Flammability:	UL94V-0
Contact:	
Material:	Copper Alloy
Plating:	See Ordering Information

Mechanical

Mating Force:	≤ 0.75N/PIN
Withdrawl Force:	≥ 0.15N/PIN
Mating and Un-mating Operations:	50

Electrical

Contact Resistance:	≤ 20 mΩ
Insulation Resistance:	≥ 10,000 MΩ
Test Voltage:	750 VAC_{RMS}

Environmental

Temperature Ratings:	-55°C to +125°C

PCB Data

Recommended PCB Plated Through Hole:	Φ 0.6±0.05 mm
Drill Hole Diameter:	Φ 0.7±0.02 mm
Hole platings:	Cu 25~50 µm, Sn or SnPb<10 µm
PCB thickness:	1.4-4.2 mm
Press-In Force:	≤ 204N/pin on nominal hole diameter
Retention Force:	≥ 13.5N/pin on nominal hole diameter

3M
Electronic Solutions Division
Interconnect Solutions
http://www.3M.com/interconnects/

For technical, sales or ordering information call
800-225-5373

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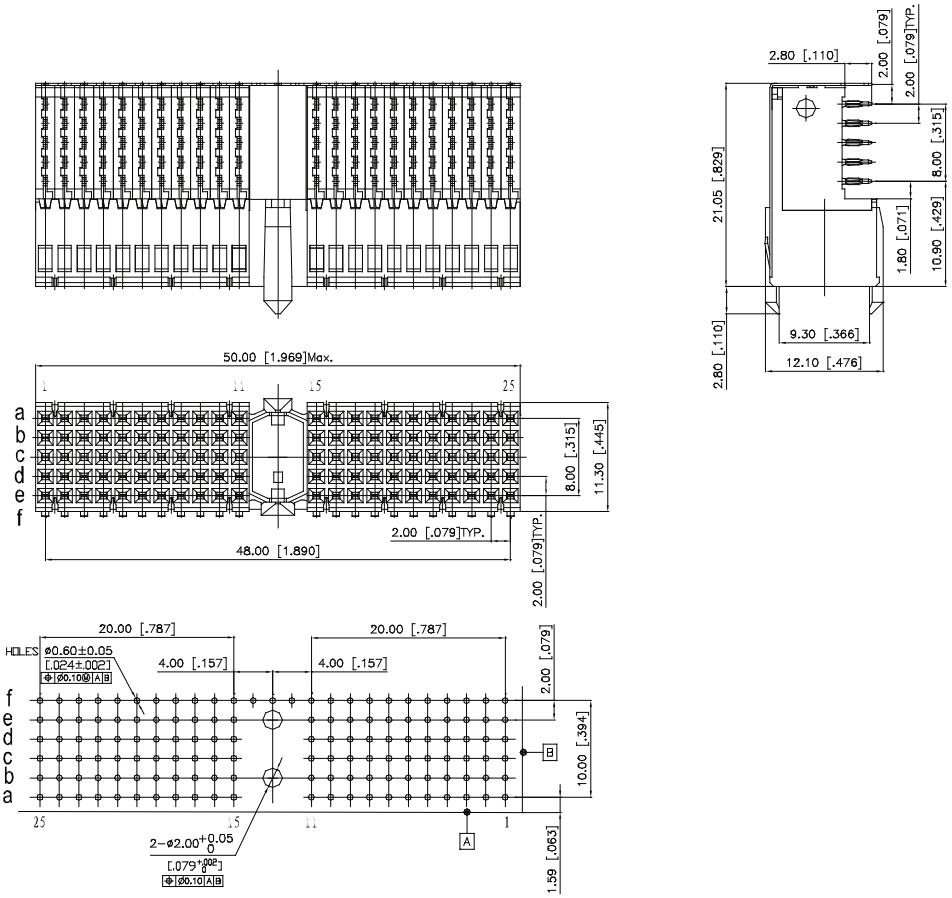
CP2 Series



Recommended PCB Layout

mm
[Inch]

Tolerance Unless Noted			
	0.	.0	.00
mm	1	0.3	0.13

[ ] Dimensions for Reference only

Ordering Information

CP2-SA110-X1-XXXX

Shield Options
G= Upper Shield
Blank= No Shield

Plating Options

TG30= 30~40 µ" Gold Contact Area
100~200 µ" Bright Tin-Lead
50~80 µ" Nickel Underplate
(RIA E2 & C2 apply)

FJ= 10~20 µ" Gold Contact Area
200~300 µ" Matte Tin
50~80 µ" Nickel Underplate
(RIA E1 & C1 apply)

KR= 30~40 µ" Gold Contact Area
200~300 µ" Matte Tin
50~80 µ" Nickel Underplate
(RIA E1 & C1 apply)

• This diagram serves only for Part Number descriptive definitions.
PLEASE CONTACT YOUR LOCAL SALES REPRESENTATIVE FOR CUSTOMER SPECIFIC PROGUCT CONFIGURATIONS.

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